imall

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Product Summary

V _{(BR)DSS}	Max R _{DS(on)}	Max I _D T _A = +25°C
250V	8.5Ω @ V _{GS} = 10V	230mA

Description and Applications

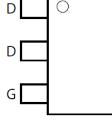
This 250V enhancement mode N-channel MOSFET provides users with a competitive specification. It offers efficient power handling capability, high impedance and is free from thermal runaway and thermally induced secondary breakdowns. Applications benefiting from this device include a variety of Telecom and general high-voltage circuits.

SOT89 and SOT223 versions are also available.

- Earth Recall and Dialing Switches
- Electronic Hook Switches
- High Voltage Power MOSFET Drivers
- Telecom Call Routers
- Solid State Relays



Top View



250V N-CHANNEL ENHANCEMENT MODE MOSFET

Features and Benefits

- High voltage
- Low on-resistance
- Fast switching speed
- Low threshold
 - Low gate drive
- Complementary P-channel Type ZVP4525E6
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

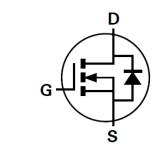
Case: SOT26

D

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S

- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.015 grams (Approximate)



Pinout Top-view

Device symbol

Ordering Information (Note 4)

Part Number	Reel Size (inch)	Tape Width (mm)	Quantity Per Reel
ZVN4525E6TA	7	8	3,000
ZVN4525E6TC	13	8	10,000

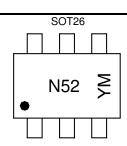
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

 See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl)

and <1000ppm antimony compounds. 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



N52 = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: C = 2015) M or \overline{M} = Month (ex: 9 = September)

Date Code Key

Duie Ooue	i toy												
Year	201	5	2016	2017	2018	2019	2020	202	1 20	22 :	2023	2024	2025
Code	С		D	E	F	G	Н			J	K	L	М
Mont	h	Jai	n Fel	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	•	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25 °C, unless otherwise specified.)

	Characteristic	;	Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	250	V
Gate-Source Voltage			V _{GS}	±40	V
Continuous Drain Current	101	T _A =+25 °C (Note 4)	– I _D	230	A
	$V_{GS} = 10V$	T _A =+70 ℃ (Note 4)		183	mA
Pulsed Drain Current (Note 6)			IDM	1.44	А
Continuous Source Current (Body Diode)			Is	1.1	А
Pulsed Source Current (Body Diode)			I _{SM}	1.44	А

Thermal Characteristics (@TA = +25 °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Power Dissipation at T_{A} =+25 °C (Note 4)	PD	1.1	W		
Linear Derating Factor		8.8	mW/℃		
Junction to Ambient (Note 4)	R _{θJA}	113	°C/W		
Junction to Ambient (Note 5)	R _{θJA}	65	°C/W		
Operating and Storage Temperature Range T _J , T _{STG} -55 to +150 ℃					
Notes: 4. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.					

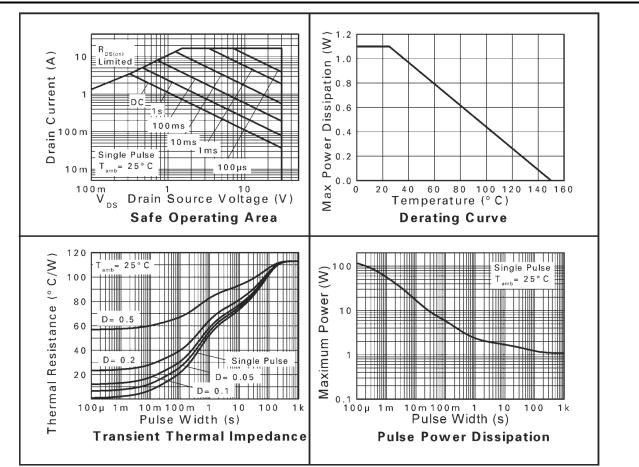
For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
For a device surface mounted on FR4 PCB measured at t≤5 secs.

6. Repetitive rating - pulse width limited by maximum junction temperature. Refer to Transient Thermal.

NB High Voltage Applications

For high voltage applications, the appropriate industry sector guidelines should be considered with regards to voltage spacing between conductors.

Thermal Characteristics





Electrical Characteristics (@ T_A = +25 °C, unless otherwise specified.)

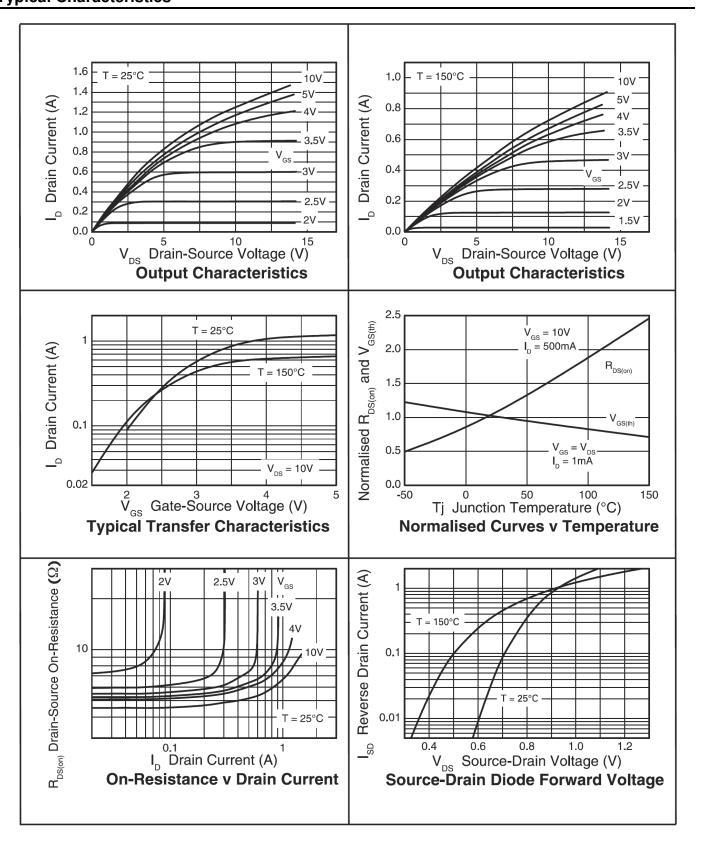
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS			- 76				
Drain-Source Breakdown Voltage	BV _{DSS}	250	285	-	V	$I_{D} = 1mA, V_{GS} = 0V$	
Zero Gate Voltage Drain Current	I _{DSS}	-	35	500	νA	V _{DS} = 250V, V _{GS} = 0V	
Gate-Body Leakage	IGSS		±1	100	nA	$V_{GS} = \pm 40V, V_{DS} = 0V$	
ON CHARACTERISTICS						-	
Gate-Source Threshold Voltage	V _{GS(th)}	0.8	1.4	1.8	V	$I_D = 1mA$, $V_{DS} = V_{GS}$	
			5.6	8.5	Ω	$V_{GS} = 10V, I_D = 500mA$	
Static Drain-Source On-State Resistance (Note 7)	R _{DS} (ON)	-	5.9	9.0	Ω	$V_{GS} = 4.5V, I_D = 360mA$	
			6.4	9.5	Ω	$V_{GS} = 2.4V, I_D = 20mA$	
Forward Transconductance (Note 9)	g _{fs}	0.3	0.475	-	S	$V_{DS} = 10V, I_D = 0.3A$	
Diode Forward Voltage (Note 7)	V _{SD}			0.97	V	T _J =+25 ℃ , I _S = 360mA, V _{GS} = 0V	
DYNAMIC CHARACTERISTICS (Notes 8 & 9)						-	
Input Capacitance	Ciss	-	72	-	pF		
Output Capacitance	Coss	-	11	-	pF	─V _{DS} = 25 V, V _{GS} = 0V ─f = 1MHz	
Reverse Transfer Capacitance	C _{rss}	-	3.6	-	pF		
Total Gate Charge	Qg	-	2.6	3.65	nC		
Gate-Source Charge	Q _{gs}	-	0.2	0.28	nC	$V_{GS} = 10V, V_{DS} = 25V$	
Gate-Drain Charge	Q _{gd}	-	0.5	0.7	nC	$-I_D = 360 \text{mA}(\text{refer to test circuit})$	
Reverse Recovery Time (Note 9)	t _{rr}	-	186	260	ns	T _J =+25 ℃, IF=360A,	
Reverse Recovery Charge (Note 9)	Q _{rr}	-	34	48	nC	di/dt= 100A/µs	
Turn-On Delay Time	t _{d(on)}	-	1.25	-	ns		
Turn-On Rise Time	tr	-	1.7	-	ns	$V_{DD} = 30V, V_{GS} = 10V$	
Turn-Off Delay Time	t _{d(off)}	-	11.40	-	ns	$I_D = 360 \text{mA}, R_G = 50 \Omega$	
Turn-Off Fall Time	tf	-	3.5	-	ns	(refer to test circuit)	

Notes:

7. Measured under pulsed conditions. Width=300µs. Duty cycle ≤ 2%.
8. Switching characteristics are independent of operating junction temperature.
9. For design aid only, not subject to production testing.

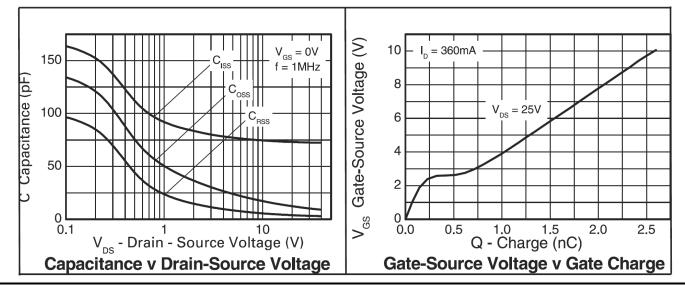


Typical Characteristics

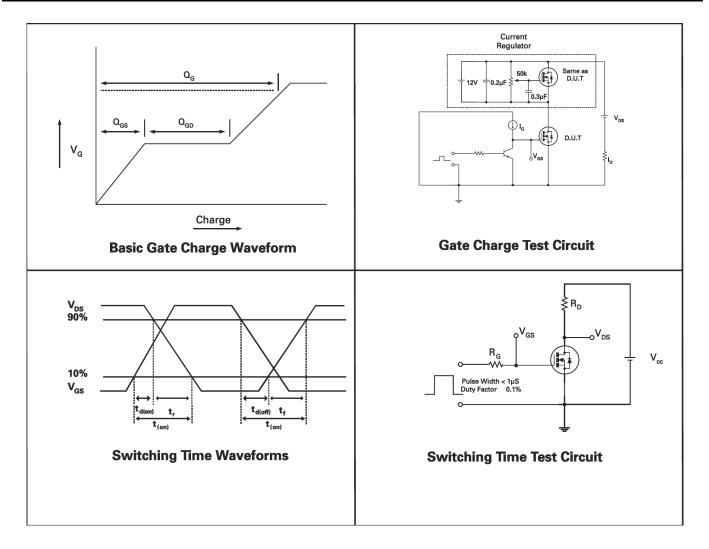




Typical Characteristics (continued)



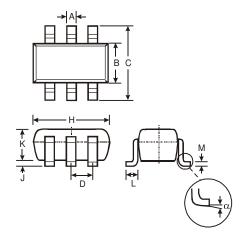
Test Circuits





Package Outline Dimensions

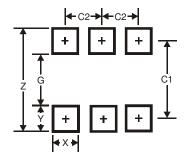
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT26							
Dim	Min	Max	Тур				
Α	0.35	0.50	0.38				
В	1.50	1.70	1.60				
С	2.70	3.00	2.80				
D			0.95				
Н	2.90	3.10	3.00				
J	0.013	0.10	0.05				
Κ	K 1.00 1.30						
L	L 0.35 0.55 0.40						
М	0.10	0.20	0.15				
α	α 0° 8° —						
aii d	All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	3.20
G	1.60
Х	0.55
Y	0.80
C1	2.40
C2	0.95



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